



SYMBOL	MIN	NOM	MAX
A	--	--	1.35
A1	0	--	0.15
A2	1.0	1.1	1.2
b	0.35	--	0.45
D	2.82	2.92	3.02
E	2.60	2.80	3.00
E1	1.526	1.626	1.726
e	0.9	0.95	1.0
L	0.35	0.45	0.6
L1	0.6REF		
L2	0.25REF		
R	0.1	--	--
R1	0.1	--	0.25
$\theta$	0°	4°	8°
$\theta 1$	5°	10°	15°

NOTES:  
 1. ALL DIMENSIONS REFER TO JEDEC STANDARD MO-178  
 2. DIMENSION D DOES NOT INCLUDE MOLD FLASH  
 3. DIMENSION E1 DOES NOT INCLUDE MOLD FLASH  
 4. FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.

 <b>上海季丰电子科技有限公司</b> GIGA FORCE ELECTRONICS CO., Limited			
制图	王磊	Title	Package Outline SOT23-5
核准	何桂港	POD No	POD-SHJF-41
日期	2022. 3. 31	DIMENSIONS IN:	mm Rev: A